501871849 03/29/2012

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Mitsuhiko Miyazaki	03/23/2012

RECEIVING PARTY DATA

Name:	Hakko Corporation	
Street Address:	4-5, Shiokusa 2-chome, Naniwa-ku, Osaka-shi	
City:	Osaka	
State/Country:	JAPAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	29417066

CORRESPONDENCE DATA

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via US Mail.

Correspondent Name: Squire Sanders (US) LLP

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Address Line 4: San Francisco, CALIFORNIA 94111

ATTORNEY DOCKET NUMBER: 62649.58

NAME OF SUBMITTER: Norman L. Morales

Total Attachments: 1

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PATENT REEL: 027958 FRAME: 0370 CH \$40.00 Z341/06

ASSIGNMENT

For value received, I (We), Mitsuhiko MIYAZAKI, residing at c/o Hakko Corporation, 4-5, Shiokusa 2-chome, Naniwa-ku, Osaka-shi, Osaka, Japan, hereby sell, assign, and transfer to HAKKO CORPORATION, a corporation existing under the laws of Japan, located at 4-5, Shiokusa 2-chome, Naniwa-ku, Osaka-shi, Osaka, Japan, and its successors, assigns, and legal representatives, the entire right, title, and interest for all countries including the United States of America, in and to certain inventions relating to

Soldering Tip

described in an application for L	etters Patent of the United Sta	tes,
[X] having an oath or declaration	on by me/us executed on even	date herewith;
[] bearing Serial No	and filed on	, and all
patents which may be granted th	erefor, and all divisions, reissu	ies, continuations and
extensions thereof, and authorize	e and request the Commissione	er of Patents and
Trademarks to issue all patents of	on said improvements or result	ing therefrom to said
Company as assignee of the entire	re interest, and covenant that I	/We have full right so
to do, and agree that I/We will c	ommunicate to said Company	or its representatives
any facts known to me/us respec	ting said improvements and te	stify in any legal
proceedings, sign all lawful pape	ers, execute all divisional, con	tinuing and reissue
applications, make all rightful oa	aths and generally do everythin	ng possible to aid said
Company, its successors, assigns	s, and nominees, to obtain and	enforce proper
protection for said invention in t	he United States.	

The Assignor(s) hereby authorizes and requests the attorneys of SQUIRE, SANDERS & DEMPSEY, L.L.P. (Customer No. 44955), to insert in the spaces provided above the filing date, serial number, and attorney docket number of said application if not previously inserted.

Signature Mitsuhiho Mujazuhi Date 3/33/30/2 Mitsuhiko MIYAZAKI

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